LITEON Opto-isolateurs

Fig. 1

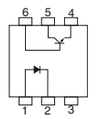


Fig. 2

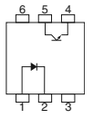


Fig. 3

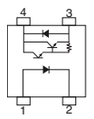


Fig. 4

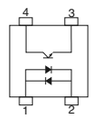


Fig. 5

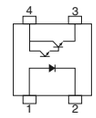


Fig. 6

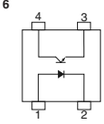


Fig. 7

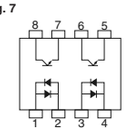


Fig. 8

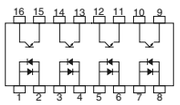


Fig. 9

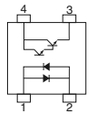


Fig. 10

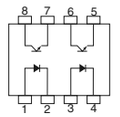


Fig. 11

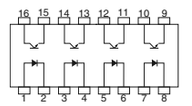


Fig. 12

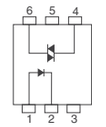


Fig. 13

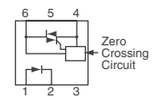


Fig.	Tension d'isolement	Rapport de transfert de courant Min.	Max.	V_{CEO} typ. (max.)	$t_{passant}/t_{bloqué}$ (µs)	Type boîtier	N° de référence Digi-Key	Prix 1	10	100	N° de référence Lite-On
1	2500	20%	–	30	3.0/3.0	DIP	160-1300-5-ND◆	.27	2.06	15.44	4N25
	2500	20%	–	30	3.0/3.0	SMT	160-1301-5-ND◆	.29	2.16	16.20	4N25S
	1500	20%	–	30	3.0/3.0	DIP	160-1302-5-ND◆	.28	2.08	15.63	4N26
	1500	20%	–	30	3.0/3.0	SMT	160-1303-5-ND◆	.29	2.16	16.20	4N26S
	3550	100%	–	30	3.0/3.0	DIP	160-1304-5-ND◆	.27	2.06	15.44	4N35
	3550	100%	–	30	3.0/3.0	SMT	160-1305-5-ND◆	.27	2.06	15.44	4N35S
	1500	100%	–	30	3.0/3.0	DIP	160-1306-5-ND◆	.27	2.06	15.44	4N37
	1500	100%	–	30	3.0/3.0	SMT	160-1307-5-ND◆	.29	2.16	16.20	4N37S
	5000	40%	80%	70	5.0/5.0	DIP	160-1308-5-ND◆	.27	2.06	15.44	CNY17-1
	5000	40%	80%	70	5.0/5.0	SMT	160-1309-5-ND◆	.29	2.16	16.20	CNY17-1S
	5000	63%	125%	70	5.0/5.0	DIP	160-1310-5-ND◆	.37	2.80	20.96	CNY17-2
	5000	63%	125%	70	5.0/5.0	SMT	160-1311-5-ND◆	.42	3.18	23.83	CNY17-2S
	5000	100%	200%	70	5.0/5.0	DIP	160-1312-5-ND◆	.27	2.06	15.44	CNY17-3
	5000	100%	200%	70	5.0/5.0	SMT	160-1313-5-ND◆	.29	2.16	16.20	CNY17-3S
	5000	160%	320%	70	5.0/5.0	DIP	160-1314-5-ND◆	.27	2.06	15.44	CNY17-4
	5000	160%	320%	70	5.0/5.0	SMT	160-1315-5-ND◆	.29	2.16	16.20	CNY17-4S
2	5000	40%	80%	70	5.0/5.0	DIP	160-1316-5-ND◆	.27	2.06	15.44	CNY17F-1
	5000	40%	80%	70	5.0/5.0	SMT	160-1317-5-ND◆	.29	2.16	16.20	CNY17F-1S
	5000	63%	125%	70	5.0/5.0	DIP	160-1318-5-ND◆	.27	2.06	15.44	CNY17F-2
	5000	63%	125%	70	5.0/5.0	SMT	160-1319-5-ND◆	.29	2.16	16.20	CNY17F-2S
	5000	100%	200%	70	5.0/5.0	DIP	160-1320-5-ND◆	.28	2.08	15.63	CNY17F-3
	5000	100%	200%	70	5.0/5.0	SMT	160-1321-5-ND◆	.29	2.16	16.20	CNY17F-3S
	5000	160%	320%	70	5.0/5.0	DIP	160-1322-5-ND◆	.27	2.06	15.44	CNY17F-4
	5000	160%	320%	70	5.0/5.0	SMT	160-1323-5-ND◆	.29	2.16	16.20	CNY17F-4S
1	5000	20%	–	30	2.8/4.5	SMT	160-1327-5-ND	.29	2.16	16.20	H11A2S
1	5000	20%	–	300	5.0/5.0	DIP	160-1328-5-ND◆	.64	4.83	36.21	H11D1
	5000	20%	–	300	5.0/5.0	SMT	160-1329-5-ND◆	.66	4.93	36.97	H11D1S
3	3750	1000%	–	300	100/20	SMT	160-1331-1-ND◆†	.43	3.63	28.97	LTV-352T
	3750	1000%	–	300	100/20	SMT	160-1331-2-ND◆‡		162.95/750		LTV-352T
4	3750	20%	400%	35	4.0/3.0	SMT	160-1333-1-ND◆†	.25	2.12	16.94	LTV-354T
	3750	20%	400%	35	4.0/3.0	SMT	160-1333-2-ND◆‡		95.29/750		LTV-354T
5	3750	600%	7500%	35	60/53	SMT	160-1335-1-ND◆†	.25	2.14	17.11	LTV-355T
	3750	600%	7500%	35	60/53	SMT	160-1335-2-ND◆‡		96.24/750		LTV-335T
6	3750	50%	600%	80	4.0/3.0	SMT	160-1337-1-ND◆†	.19	1.59	12.71	LTV-356T
	3750	50%	600%	80	4.0/3.0	SMT	160-1337-2-ND◆‡		71.47/750		LTV-356T
	3750	50%	600%	35	4.0/3.0	SMT	160-1339-1-ND◆†	.19	1.59	12.71	LTV-357T
	3750	50%	600%	35	4.0/3.0	SMT	160-1339-2-ND◆‡		71.47/750		LTV-357T
2	5000	40%	320%	70	2.0/2.0	DIP	160-1340-5-ND	.27	2.06	15.44	LTV-702F
	5000	40%	320%	70	2.0/2.0	SMT	160-1341-5-ND◆	.29	2.16	16.20	LTV-702FS
1	5000	40%	320%	70	2.0/2.0	DIP	160-1342-5-ND	.27	2.06	15.44	LTV-702V
4	5000	20%	300%	35	4.0/3.0	DIP	160-1344-5-ND◆	.30	2.24	16.77	LTV-814
	5000	20%	300%	35	4.0/3.0	SMT	160-1345-5-ND◆	.30	2.31	17.35	LTV-814S
7	5000	20%	300%	35	4.0/3.0	DIP	160-1346-5-ND◆	.59	4.45	33.35	LTV-824

Fig.	Tension d'isolement	Rapport de transfert de courant Min.	Max.	V_{CEO} typ. (max.)	$t_{passant}/t_{bloqué}$ (µs)	Type boîtier	N° de référence Digi-Key	Prix 1	10	100	N° de référence Lite-On
7	5000	20%	300%	35	4.0/3.0	SMT	160-1347-5-ND◆	.61	4.55	34.12	LTV-824S
8	5000	20%	300%	35	4.0/3.0	DIP	160-1348-5-ND◆	1.19	8.89	66.70	LTV-844
	5000	20%	300%	35	4.0/3.0	SMT	160-1349-5-ND◆	1.20	9.00	67.46	LTV-844S
4	5000	20%	80%	35	4.0/3.0	DIP	160-1350-5-ND◆	.34	2.54	19.06	LTV-814H
	5000	20%	80%	35	4.0/3.0	SMT	160-1351-5-ND◆	.36	2.64	19.82	LTV-814HS
7	5000	20%	80%	35	4.0/3.0	DIP	160-1352-5-ND◆	.68	5.08	38.12	LTV-824H
9	5000	600%	7500%	35	60/53	DIP	160-1356-5-ND◆	.53	4.01	30.11	LTV-8141
	5000	600%	7500%	35	60/53	SMT	160-1357-5-ND◆	.54	4.09	30.69	LTV-8141S
5	5000	600%	7500%	35	60/53	DIP	160-1358-5-ND◆	.27	2.01	15.06	LTV-815
	5000	600%	7500%	35	60/53	SMT	160-1359-5-ND◆	.28	2.11	15.82	LTV-815S
6	5000	50%	600%	80	4.0/3.0	DIP	160-1360-5-ND◆	.21	1.60	12.01	LTV-816
	5000	50%	600%	80	4.0/3.0	SMT	160-1361-5-ND◆	.22	1.68	12.58	LTV-816S
10	5000	50%	600%	80	4.0/3.0	DIP	160-1362-5-ND◆	.42	3.18	23.83	LTV-826
	5000	50%	600%	80	4.0/3.0	SMT	160-1363-5-ND◆	.44	3.28	24.59	LTV-826S
11	5000	50%	600%	80	4.0/3.0	DIP	160-1364-5-ND◆	.85	6.35	47.64	LTV-846
	5000	50%	600%	80	4.0/3.0	SMT	160-1365-5-ND◆	.86	6.45	48.41	LTV-846S
6	5000	50%	600%	35	4.0/3.0	DIP	160-1366-5-ND◆	.21	1.60	12.01	LTV-817
	5000	50%	600%	35	4.0/3.0	SMT	160-1367-5-ND◆	.22	1.68	12.58	LTV-817S
10	5000	50%	600%	35	4.0/3.0	DIP	160-1368-5-ND◆	.42	3.18	23.83	LTV-827
	5000	50%	600%	35	4.0/3.0	SMT	160-1369-5-ND◆	.44	3.28	24.59	LTV-827S
11	5000	50%	600%	35	4.0/3.0	DIP	160-1370-5-ND◆	.85	6.35	47.64	LTV-847
	5000	50%	600%	35	4.0/3.0	SMT	160-1371-5-ND◆	.86	6.45	48.41	LTV-847S

◆ ***Conforme à RoHS*** † Bande coupée ‡ Bande et bobine

Opto-isolateurs de sortie à triac

RoHS COMPLIANT

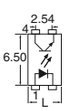
Fig.	Max. I_F Isolation Voltage††	Min. Trigger (mA)‡‡	Tension de blocage max.	I_R (µA)	Type de boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100	N° de référence Lite-On
12	5000	30	400V	10	DIP	160-1372-5-ND	.53	.41	.31	MOC3020
	5000	30	400V	10	SMT	160-1373-5-ND	.54	.41	.31	MOC3020S
	5000	15	400V	10	DIP	160-1374-5-ND	.53	.41	.31	MOC3021
	5000	15	400V	10	SMT	160-1375-5-ND	.54	.41	.31	MOC3021S
	5000	10	400V	10	DIP	160-1376-5-ND	.53	.41	.31	MOC3022
	5000	10	400V	10	SMT	160-1377-5-ND	.54	.41	.31	MOC3022S
	5000	5	400V	10	DIP	160-1378-5-ND	.53	.41	.31	MOC3023
	5000	5	400V	10	SMT	160-1379-5-ND	.54	.41	.31	MOC3023S
13	5000	5	600V	10	DIP	160-1722-5-ND	.42	.35	.28	MOC3063
	5000	5	600V	10	SMT	160-1723-1-ND†	.45	.38	.30	MOC3063S-TA1
	5000	5	600V	10	SMT	160-1723-2-ND‡		223.61/1,000		MOC3063S-TA1

† Bande coupée ‡ Bande et bobine †† Tension d'isolement de fréquence intermédiaire max.
‡‡ Tension de déclenchement min. (mA)

Optoliens

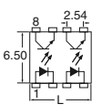
Spécifications : • Tension d'isolement : 5 000 • V_{CEO} (max.) : 60 V • Tr/tf typique : 5 µs/4 µs

Fig. 1



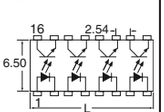
Boîtier DIL ou CMS de sortie du phototransistor

Fig. 2



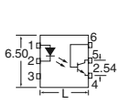
Boîtier DIL ou CMS de sortie du phototransistor double

Fig. 3



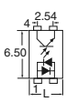
Boîtier DIL ou CMS de sortie du phototransistor quadruple

Fig. 4



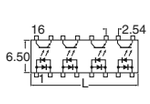
Boîtier DIL ou CMS de sortie du phototransistor

Fig. 5



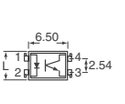
Boîtier DIL ou CMS de sortie du phototransistor

Fig. 6



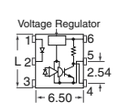
Boîtier DIL ou CMS de sortie du phototransistor quadruple

Fig. 7



Boîtier DIL de phototransistor mono-canal

Fig. 8



Boîtier DIL ou CMS de sortie du photo IC

Opto-isolateurs avec sortie phototransistor

Fig.	Rapport de transfert de courant min.-max.	Longueur « L » (mm)	Boîtier	N° de référence Digi-Key	Prix unitaire 1	10	Prix de bande et de bobine ‡	N° de référence Lumex
1	60-600%	4.60	SMT	67-1613-1-ND◆†	.43	.36	—	OCP-PCT114/E-TR
2	60-600%	9.68	SMT	67-1614-1-ND†	.89	.75	—	OCP-PCT218/E-TR
3	60-600%	19.84	SMT	67-1618-5-ND◆	1.55	1.30	—	OCP-PCT4116/E-TR
4	60-600%	7.30	DIP	67-1563-5-ND◆	.33	.28	—	OCP-PCTB116/E
	60-600%	7.30	SMT	67-1615-1-ND◆†	.33	.28	182.78/1,000	OCP-PCTB116/E-TR
5	60-600%	4.60	DIP	67-1564-5-ND◆	.53	.45	—	OCP-PCT124/A
	60-600%	4.60	SMT	67-1616-1-ND◆†	.53	.45	—	OCP-PCT124/A-TR
6	60-600%	19.84	DIP	67-1565-5-ND◆	2.44	2.04	—	OCP-PCT4216/A
7	200-400%	4.60	DIP	67-2044-5-ND	.22	.19	—	OCP-PCT114/C

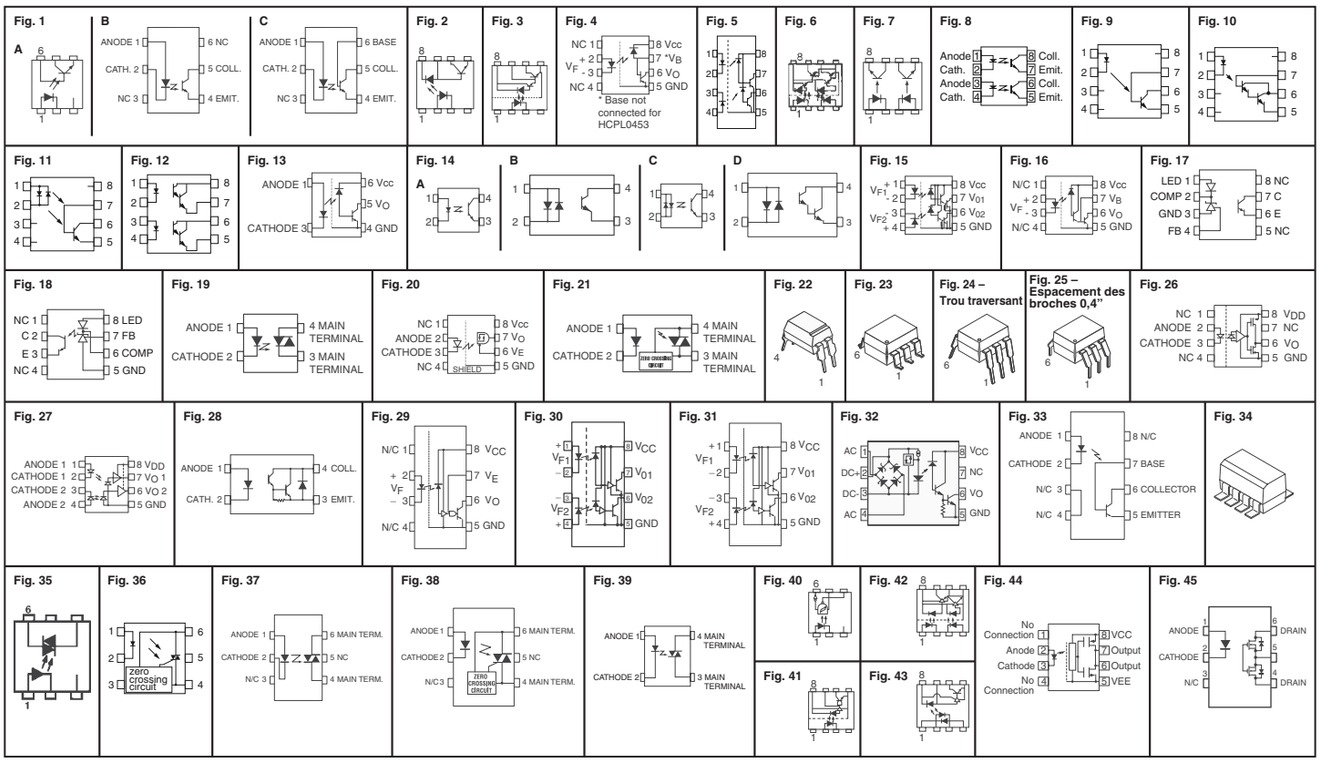
Opto-isolateurs avec sortie photo IC

Fig.	Tension d'isolement	Temps de propagation t_{PHL}/t_{PLH} (µs)	Longueur « L » (mm)	Boîtier	N° de référence Digi-Key	Prix unitaire 1	10	Prix de bande et bobine 1 000‡	N° de référence Lumex
8	5000	5/3	7.3	DIP	67-1566-5-ND◆	1.39	1.16	—	OCP-PCP116
	5000	5/3	7.3	SMT	67-1617-1-ND†	1.39	1.16	766.28	OCP-PCP116-TR

◆ ***Conforme à RoHS*** † Bande coupée ‡ Pour obtenir le numéro de référence de bande et de bobine, remplacer 1-ND par 2-ND.

N

Opto-isolateurs



Opto-isolateurs de sortie de phototransistor

Fig.	Tension d'isolement	Rapport de transfert de courant - Type (%) (Min.)	Typique	max.)	VCEO (max.)	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
1A	5300	20	70	—	30	DIP	4N25MFS-ND◆	.47	.38	.27
	5300	20	70	—	30	SMD	4N25SM-ND◆	.47	.38	.27
	5300	20	70	—	30	DIP	4N26MFS-ND◆	.47	.38	.27
	5300	10	50	—	30	DIP	4N27MFS-ND◆	.47	.38	.27
	5300	100	300	—	30	SMD	4N35MFS-ND◆	.47	.38	.27
	5300	100	300	—	30	SMD	4N35SM-ND◆	.47	.38	.27
	5300	100	300	—	30	DIP	4N36M-ND◆	.47	.38	.27
	5300	100	300	—	30	DIP	4N37MFS-ND◆	.47	.38	.27
	5300	40	60	80	70	DIP	CNY171MFS-ND	.47	.38	.27
	5300	63	100	125	70	DIP	CNY172M-ND◆	.47	.38	.27
	5300	100	150	200	70	DIP	CNY173M-ND◆	.47	.38	.27
	5300	50	120	—	30	SMD	H11A1SM-ND◆	.47	.38	.27
	5300	100	—	300	70	DIP	H11AV1AM-ND◆▲	.68	.53	.38
	5300	100	—	300	70	DIP	H11AV1M-ND	.68	.53	.38
	5300	50	100	—	30	DIP	MOC8100M-ND	.47	.38	.27
	7500	100	—	—	30	SMD	4N35SR2MCT-ND‡◆	.62	.48	.35
	7500	100	—	—	30	SMD	4N35SR2MTR-ND◊◆	183.74/1,000		
	7500	400	—	150	30	DIP	MCT210M-ND◆	.64	.49	.37
1B	5300	160	—	320	70	DIP	CNY174MFS-ND◆	.47	.36	.26
1C	5300	40	—	80	70	DIP	CNY17F1MFS-ND◆	.54	.43	.31
	5300	63	—	125	70	SMD	CNY17F2MFS-ND◆	.50	.40	.29
	5300	100	—	200	70	DIP	CNY17F3MFS-ND◆	.50	.40	.29
	5300	160	—	320	70	SMD	CNY17F4MFS-ND◆	.50	.40	.29
	5300	40	—	80	70	DIP	CNY17F1TVM-ND◆	.50	.40	.29
	5300	50	—	150	70	SMD	MOC8106SM-ND◆	.58	.46	.33
2	2500	7	18	50	15	DIP	6N135QT-ND◆	.94	.77	.54
	2500	19	27	50	15	DIP	6N136QT-ND◆	.94	.77	.54
	2500	12	27	—	15	DIP	HCPL2503QT-ND◆	1.10	.90	.62
3	2500	300	1300	—	7	DIP	6N138QT-ND◆	.98	.80	.56
	2500	400	1100	—	18	DIP	6N139QT-ND◆	.98	.80	.56
4	2500	15	—	50	—	SOIC	FOD050LR1CT-ND‡◆	1.80	1.62	1.05
	2500	15	—	50	—	SOIC	FOD050LR1TR-ND◊◆	379.46/500		
	2500	19	27	50	—	SOIC	HCPL0453R1CT-ND‡◆	2.16	1.93	1.25
	2500	19	27	50	—	SOIC	HCPL0453R1TR-ND◊◆	453.99/500		
	2500	19	27	50	—	SMD	HCPL0501-ND◆	1.63	1.45	.94
	2500	7	2.7	50	—	SOIC	HCPL0530R1CT-ND‡◆	3.52	2.94	2.14
	2500	7	2.7	50	—	SOIC	HCPL0530R1TR-ND◊◆	773.73/500		
	2500	19	27	50	—	SOIC	HCPL0531R1CT-ND‡◆	3.94	3.29	2.39
	2500	19	27	50	—	SOIC	HCPL0531R1TR-ND◊◆	865.85/500		
	2500	15	30	—	—	SOIC	HCPL0534R1CT-ND‡◆	4.34	3.62	2.63
	2500	15	30	—	—	SOIC	HCPL0534R1TR-ND◊◆	1746.09/1,000		
	5000	19	27	50	—	DIP	HCPL4503M-ND◆	1.42	1.16	.81
	5000	19	27	50	—	SMD	HCPL4503SDMCT-ND‡◆	2.09	1.88	1.22
	5000	19	27	50	—	SMD	HCPL4503SDMTR-ND◊◆	757.01/1,000		
	5000	19	27	50	—	SMD	HCPL4503SM-ND◆	1.93	1.71	1.11
	5000	19	27	50	—	DIP	HCPL4503TM-ND◆	1.93	1.71	1.11
5	2500	15	—	50	—	SOIC	FOD053LR1CT-ND‡◆	3.24	2.71	1.97
	2500	15	—	50	—	SOIC	FOD053LR1TR-ND◊◆	712.33/500		
	2500	16	18	—	—	DIP	HCPL2530-ND◆	2.08	1.85	1.19
6	2500	19	27	—	—	DIP	HCPL2531-ND◆	2.08	1.85	1.19
	2500	300	—	—	7	DIP	HCPL2730QT-ND◆	2.08	1.85	1.19
	2500	400	—	—	18	DIP	HCPL2731QT-ND◆	1.80	1.59	1.03
7	2500	20	—	—	30	DIP	MCT6-ND◆	.77	.61	.43
7	2500	50	—	—	30	DIP	MCT61-ND◆	.77	.61	.43
	2500	100	—	—	30	DIP	MCT62-ND◆	.82	.64	.46
	2500	10	—	—	30	SMD	MCT62S-ND◆	.82	.64	.46
8	2500	50	—	600	55	DIP	MCT9001-ND◆	.82	.64	.46
	2500	100	150	200	70	SMD	MOCD207M-ND◆	.91	.74	.52
	2500	40	—	125	70	SMD	MOCD208M-ND◆	.97	.79	.55
	2500	20	65	—	30	SMD	MOCD211M-ND◆	.97	.79	.55
	2500	100	—	—	70	SMD	MOCD213M-ND◆	.95	.78	.54
	2500	100	—	—	70	SOIC	MOCD213R2MCT-ND‡◆	1.13	.91	.64
	2500	100	—	—	70	SOIC	MOCD213R2MTR-ND◊◆	839.48/2,500		
	2500	100	130	—	30	SMD	MOCD217M-ND◆	.97	.79	.55
	2500	100	—	—	30	SOIC	MOCD217R2MCT-ND‡◆	1.05	.84	.59
	2500	100	—	—	30	SOIC	MOCD217R2MTR-ND◊◆	775.61/2,500		
9	3000	40	60	80	70	SMD	MOC205M-ND	.60	.48	.34
	3000	63	94	125	70	SMD	MOC206M-ND◆	.60	.48	.34
	3000	100	150	200	70	SMD	MOC207M-ND◆	.58	.46	.33
	3000	40	80	125	70	SMD	MOC208M-ND	.60	.48	.34
	3000	20	65	—	30	SMD	MOC211M-ND◆	.60	.48	.34
	3000	50	90	—	30	SMD	MOC212M-ND◆	.60	.48	.34
	3000	100	140	—	30	SMD	MOC213M-ND◆	.60	.48	.34
	3000	20	—	—	30	SMD	MOC215M-ND	.60	.48	.34
	3000	100	—	—	30	SMD	MOC217M-ND◆	.60	.48	.34
10	3000	500	1000	—	30	SOIC	MOC223M-ND◆	.69	.54	.39
11	3000	20	150	—	30	SOIC	MOC256M-ND◆	.84	.66	.47
12	2500	500	1000	—	30	SMD	MOCD223M-ND◆	1.10	.90	.62
13	3750	20	—	50	—	MFP	FODM452R1VCT-ND‡◆	1.84	1.65	1.07
	3750	20	—	50	—	MFP	FODM452R1VTR-ND◊◆	386.23/500		
	3750	20	—	50	—	MFP	FODM453R1VCT-ND‡◆	1.90	1.70	1.10
	3750	20	—	50	—	MFP	FODM453R1VTR-ND◊◆	399.78/500		
14A	2500	80	—	600	80	MFP	HMHA2801-ND◆	.44	.36	.27
	2500	80	—	600	80	MFP	HMHA2801R1CT-ND‡◆	.41	.31	.24
	2500	80	—	600	80	MFP	HMHA2801R1TR-ND◊◆	136.37/1,000		
	2500	80	—	600	80	MFP	HMHA2801R2CT-ND‡◆	.41	.31	.24
	2500	80	—	600	80	MFP	HMHA2801R2TR-ND◊◆	332.45/2,500		
	2500	100	—	—	75	BGA	FODB100VCT-ND‡◆	1.31	1.05	.79
	3750	50	—	600	80	MFP	FODM121R2CT-ND‡◆	.58	.45	.33
	3750	50	—	600	80	MFP	FODM121R2TR-ND◊◆	428.79/2,500		
	3750	100	—	1200	80	MFP	FODM124R2CT-ND‡◆	.55	.44	.31
	3750	100	—	1200	80	MFP	FODM124R2TR-ND◊◆	415.07/2,500		
	3750	50	—	300	40	MFP	FODM2701R2CT-ND‡◆	.55	.44	.31
	3750	50	—	300	40	MFP	FODM2701R2TR-ND◊◆	415.07/2,500		
14C	3750	50	—	300	40	MFP	FODM2705R2CT-ND‡◆	.58	.46	.33
	3750	50	—	300	40	MFP	FODM2705R2TR-ND◊◆	439.08/2,500		
15	2500	300	—	5000	—	SOIC	HCPL0730R1CT-ND‡◆	3.52	2.94	2.14
	2500	300	—	5000	—	SOIC	HCPL0730R1TR-ND◊◆	773.73/500		
	2500	500	—	5000	—	SOIC	HCPL0731R1CT-ND‡◆	3.94	3.29	2.39
	2500	500	—	5000	—	SOIC	HCPL0731R1TR-ND◊◆	865.85/500		
16	2500	400	1100	—	—	SMD	6N139SDCT-ND‡◆	1.19	.96	.67

† Approbation VDE ▲ Écartement entre les broches : 0,4" ‡ Bande coupée ◊ Bande et bobine ◆ ***Conforme à RoHS*** *(suite)*

Opto-isolateurs

Digi-Reel®

Opto-isolateurs de sortie de phototransistor *(suite)*

Fig.	Tension d'isolement	Rapport de transfert de courant - Type (%) (Min.)	Typique	max.)	V_{CEO} (max.)	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
16	2500	400	1100	—	—	SMD	6N139SDTR-ND◊◆		371.39/1,000	
	2500	400	—	7000	—	SOIC	FOD073LR1CT-ND‡◆	4.02	3.36	2.44
	2500	400	—	7000	—	SOIC	FOD073LR1TR-ND◊◆		884.27/500	
17	5000	50	—	100	70	SMD	FOD2743ASDVCT-ND‡◆	1.52	1.22	.85
	5000	50	—	100	70	SMD	FOD2743ASDVTR-ND◊◆		474.32/1,000	
	5000	50	—	100	70	SMD	FOD2743BSDVCT-ND‡◆	1.11	.89	.62
	5000	50	—	100	70	SMD	FOD2743BSDVTR-ND◊◆		343.88/1,000	
	5000	50	—	100	70	SMD	FOD2743CSDVCT-ND‡◆	1.07	.86	.60
	5000	50	—	100	70	SMD	FOD2743CSDVTR-ND◊◆		332.02/1,000	
18	5000	100	—	200	30	DIP	FOD2711TV-ND†◆	.82	.64	.46
	2500	100	—	200	30	SOIC	FOD2712R1VCT-ND†‡◆	1.22	.98	.68
	2500	100	—	200	30	SOIC	FOD2712R1VTR-ND†◊◆		230.38/500	
	5000	100	—	200	30	SMD	FOD2741ASDVCT-ND‡‡◆	1.52	1.22	.85
	5000	100	—	200	30	SMD	FOD2741ASDVTR-ND†◊◆		474.32/1,000	
	5000	100	—	200	30	SMD	FOD2741BSDVCT-ND‡‡◆	1.11	.89	.62
	5000	100	—	200	30	SMD	FOD2741BSDVTR-ND†◊◆		343.88/1,000	
	5000	100	—	200	30	SMD	FOD2741CSDVCT-ND‡‡◆	.71	.60	.48
	2500	100	140	200	70	SOIC	FOD2742AR1VCT-ND‡‡◆	1.34	1.07	.75
	2500	100	140	200	70	SOIC	FOD2742AR1VTR-ND†◊◆		415.03/1,000	
	2500	100	140	200	70	SOIC	FOD2742BR1VCT-ND‡‡◆	1.03	.83	.58
	2500	100	140	200	70	SOIC	FOD2742BR1VTR-ND†◊◆		194.39/500	
	2500	100	140	200	70	SOIC	FOD2742CR1VCT-ND‡‡◆	.96	.77	.53
	2500	100	140	200	70	SOIC	FOD2742CR1VTR-ND†◊◆		179.99/500	
19	5000	1000	4000	15000	300	DIP	FOD852-ND◆	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD852S-ND◆	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD852SDCT-ND‡◆	.74	.58	.42
	5000	1000	4000	15000	300	SMD	FOD852SDTR-ND◊◆		246.99/1,000	
	5000	1000	4000	15000	300	DIP	FOD852W-ND▲◆	.70	.55	.39
	5000	1000	4000	15000	300	DIP	FOD852300-ND†◆	.70	.55	.39
	5000	1000	4000	15000	300	DIP	FOD852300W-ND†▲◆	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD8523S-ND†◆	.70	.55	.39
	5000	1000	4000	15000	300	SMD	FOD8523SDCT-ND†‡◆	.74	.58	.42
	5000	1000	4000	15000	300	SMD	FOD8523SDTR-ND†◊◆		461.04/2,000	
20	2500	—	—	—	—	DIP	HCPL3700-ND◆	2.91	2.59	1.67
21	2500	100	—	200	70	SMD	MOC207R1MCT-ND‡◆	.70	.55	.39
	2500	100	—	200	70	SMD	MOC207R1MTR-ND◊◆		133.83/500	
	2500	100	—	200	70	SMD	MOC207R2MCT-ND‡◆	.66	.52	.37
	2500	100	—	200	70	SMD	MOC207R2MTR-ND◊◆		464.24/2,500	
	2500	100	—	200	70	SOIC	MOCD207R1MCT-ND‡◆	1.07	.86	.60
	2500	100	—	200	70	SOIC	MOCD207R1MTR-ND◊◆		202.16/500	
	2500	100	—	200	70	SOIC	MOCD207R2MCT-ND‡◆	1.07	.86	.60
	2500	100	—	200	70	SOIC	MOCD207R2MTR-ND◊◆		790.81/2,500	
22	5000	40	—	80	70	SMD	FOD617AS-ND†◆	.43	.32	.21
	5000	40	—	80	70	SMD	FOD617A3S-ND†◆	.43	.32	.21
	5000	63	—	125	70	SMD	FOD617B3SDCT-ND†‡◆	.56	.43	.28
	5000	63	—	125	70	SMD	FOD617B3SDTR-ND†◊◆		143.25/1,000	
23	7500	100	—	—	60	SMD	4N29SM-ND◆	.56	.44	.32
	7500	100	—	—	60	SMD	4N29SR2MCT-ND‡◆	.65	.51	.36
	7500	100	—	—	60	SMD	4N29SR2MTR-ND◊◆		196.22/1,000	
	7500	100	—	—	60	SMD	4N30SM-ND◆	.56	.44	.32
	7500	100	—	—	60	SMD	4N30SR2MCT-ND‡◆	.65	.51	.36
	7500	100	—	—	60	SMD	4N30SR2MTR-ND◊◆		196.22/1,000	
	7500	500	—	—	60	SMD	4N32SM-ND◆	.56	.44	.32
	7500	20	—	—	80	SMD	4N38SR2MCT-ND‡◆	.91	.71	.51
	7500	20	—	—	80	SMD	4N38SR2MTR-ND◊◆		274.43/1,000	
	7500	40	—	80	70	SMD	CNY17F1SM-ND◆	.50	.40	.29
	7500	300	—	—	30	SMD	H11AG1SM-ND◆	.90	.71	.51
	7500	300	—	—	30	SMD	H11AG1SR2MCT-ND‡◆	.99	.80	.56
	7500	300	—	—	30	SMD	H11AG1SR2MTR-ND◊◆		308.64/1,000	
	7500	500	—	—	60	SMD	H11B1SM-ND◆	.56	.44	.32
	7500	500	—	—	60	SMD	H11B1SR2MCT-ND‡◆	.65	.51	.36
	7500	500	—	—	60	SMD	H11B1SR2MTR-ND◊◆		196.22/1,000	
	7500	500	—	—	60	SMD	H11B1SR2VMCT-ND‡◆	.65	.51	.36
	7500	500	—	—	60	SMD	H11B1SR2VMTR-ND◊◆		196.22/1,000	
	7500	20	—	—	300	SMD	H11D1SM-ND◆	.77	.61	.43
	7500	20	—	—	300	SMD	H11D1SR2MCT-ND‡◆	.91	.71	.51
	7500	20	—	—	300	SMD	H11D1SR2MTR-ND◊◆		274.43/1,000	
	7500	20	—	—	300	SMD	H11D1SR2VMCT-ND‡◆	.91	.71	.51
	7500	20	—	—	300	SMD	H11D1SR2VMTR-ND◊◆		274.43/1,000	
	7500	20	—	—	300	SMD	H11D2SR2MCT-ND‡◆	.91	.71	.51
	7500	20	—	—	300	SMD	H11D2SR2MTR-ND◊◆		274.43/1,000	
	7500	20	—	—	300	SMD	H11D2SR2VMCT-ND‡◆	.91	.71	.51
	7500	20	—	—	300	SMD	H11D2SR2VMTR-ND◊◆		274.43/1,000	
	7500	20	—	—	200	SMD	H11D3SM-ND◆	.77	.61	.43
	7500	20	—	—	200	SMD	H11D3SR2MCT-ND‡◆	.91	.71	.51
	7500	20	—	—	200	SMD	H11D3SR2MTR-ND◊◆		274.43/1,000	
	7500	—	—	200	30	SMD	H11F1SM-ND◆	2.43	2.16	1.40
	7500	—	—	200	30	SMD	H11F1SR2MCT-ND‡◆	2.68	2.40	1.55
	7500	—	—	200	30	SMD	H11F1SR2MTR-ND◊◆		968.50/1,000	
	7500	—	—	470	15	SMD	H11F3SM-ND◆	2.43	2.16	1.40
	7500	—	—	470	15	SMD	H11F3SR2MCT-ND‡◆	2.68	2.40	1.55
	7500	—	—	470	15	SMD	H11F3SR2MTR-ND◊◆		968.50/1,000	
	7500	—	—	470	15	SMD	H11F3SR2VMCT-ND‡◆	2.68	2.40	1.55
	7500	—	—	470	15	SMD	H11F3SR2VMTR-ND◊◆		968.50/1,000	
	7500	—	—	470	15	SMD	H11F3SVM-ND◆	2.43	2.16	1.40
	7500	1000	—	—	100	SMD	H11G1SM-ND◆	.78	.61	.44
	7500	1000	—	—	100	SMD	H11G1SR2MCT-ND‡◆	.92	.71	.51
	7500	1000	—	—	100	SMD	H11G1SR2MTR-ND◊◆		275.80/1,000	
	7500	500	—	—	80	SMD	H11G2SM-ND◆	.78	.61	.44
	7500	500	—	—	80	SMD	H11G2SR2MCT-ND‡◆	.92	.71	.51
	7500	500	—	—	80	SMD	H11G2SR2MTR-ND◊◆		275.80/1,000	
	7500	200	—	—	55	SMD	H11G3SR2MCT-ND‡◆	.93	.72	.52
	7500	200	—	—	55	SMD	H11G3SR2MTR-ND◊◆		279.92/1,000	
	7500	120	—	—	100	SMD	MCT5201SM-ND◆	.90	.71	.51
	7500	120	—	—	100	SMD	MCT5201SR2MCT-ND‡◆	.99	.80	.56
	7500	120	—	—	100	SMD	MCT5201SR2MTR-ND◊◆		308.64/1,000	
	7500	60	—	—	100	SMD	MCT5210SM-ND◆	.90	.71	.51
	7500	100	—	—	100	SMD	MCT5211SR2MCT-ND‡◆	1.02	.82	.57
	7500	100	—	—	100	SMD	MCT5211SR2MTR-ND◊◆		318.89/1,000	
	7500	1,000	—	—	100	SMD	MOC8021SR2MCT-ND‡◆	.85	.66	.47
	7500	1,000	—	—	100	SMD	MOC8021SR2MTR-ND◊◆		255.22/1,000	
	7500	500	—	—	100	SMD	MOC8050SR2MCT-ND‡◆	.92	.71	.51
	7500	500	—	—	100	SMD	MOC8050SR2MTR-ND◊◆		275.801,000	
	7500	20	—	—	400	SMD	MOC8204SM-ND◆	1.22	1.00	.69
23	7500	20	—	—	400	SMD	MOC8204SR2MCT-ND‡◆	1.42	1.14	.80
	7500	20	—	—	400	SMD	MOC8204SR2MTR-ND◊◆		443.11/1,000	
	7500	300	—	—	60	SMD	TIL113SM-ND◆	.62	.48	.35
24	7500	100	—	—	60	DIP	4N29M-ND◆	.56	.44	.32
	7500	100	—	—	60	DIP	4N30M-ND◆	.56	.44	.32
	7500	500	—	—	60	DIP	4N32M-ND◆	.56	.44	.32
	7500	500	—	—	60	DIP	4N32VM-ND◆	.56	.44	.32
	7500	500	—	—	60	DIP	4N33M-ND◆	.51	.40	.29
	7500	500	—	—	60	DIP	4N33VM-ND◆	.56	.44	.32
	7500	20	—	—	80	DIP	4N38M-ND◆	.77	.61	.43
	7500	300	—	—	30	DIP	H11AG1M-ND◆	.90	.71	.51
	7500	300	—	—	30	DIP	H11AG1VM-ND◆	.90	.71	.51
	7500	500	—	—	60	DIP	H11B1M-ND◆	.56	.44	.32
	7500	500	—	—	60	DIP	H11B1VM-ND◆	.56	.44	.32
	7500	20	—	—	300	DIP	H11D1MFS-ND◆	.77	.61	.43
	7500	20	—	—	300	DIP	H11D1VM-ND◆	.77	.61	.43
	7500	20	—	—	300	DIP	H11D2M-ND◆	.77	.61	.43
	7500	20	—	—	300	DIP	H11D2VM-ND◆	.77	.61	.43
	7500	20	—	—	200	DIP	H11D3M-ND◆	.77	.61	.43
	7500	—	—	200	30	DIP	H11F1M-ND◆	2.23	1.97	1.28
	7500	—	—	200	30	DIP	H11F1VM-ND◆	2.43	2.16	1.40
	7500	—	—	330	30	DIP	H11F2M-ND◆	2.43	2.16	1.40
	7500	—	—	470	15	DIP	H11F3M-ND◆	2.08	1.84	1.19
	7500	—	—	470	15	DIP	H11F3VM-ND◆	2.43	2.16	1.40
	7500	1000	—	—	100	DIP	H11G1M-ND◆	.78	.61	.44
	7500	500	—	—	80	DIP	H11G2M-ND◆	.78	.61	.44
	7500	200	—	—	55	DIP	H11G3M-ND◆	.76	.60	.43
	7500	120	—	—	100	DIP	MCT5201M-ND◆	.90	.71	.51
	7500	60	—	—	100	DIP	MCT5210M-ND◆	.90	.71	.51
	7500	100	—	—	100	DIP	MCT5211M-ND◆	.86	.71	.49
	7500	1,000	—	—	100	DIP	MOC8021M-ND◆	.66	.52	.37
	7500	500	—	—	100	DIP	MOC8050M-ND◆	.79	.62	.44
	7500	50	—	150	70	DIP	MOC8106M-ND◆	.60	.47	.34
	7500	20	—	—	70	DIP	MOC8111M-ND◆	.53	.41	.30
	7500	50	—	—	70	DIP	MOC8112M-ND◆	.53	.41	.30
	7500	100	—	—	70	DIP	MOC8113M-ND◆	.53	.41	.30
	7500	20	—	—	400	DIP	MOC8204M-ND◆	1.22	1.00	.69
	7500	300	—	—	60	DIP	TIL113M-ND◆	.70	.55	.39
25	7500	100	—	—	60	DIP	4N29TM-ND◆	.56	.44	.32
	7500	500	—	—	60	DIP	4N32TVM-ND◆	.56	.44	.32
	7500	300	—	—	30	DIP	H11AG1TVM-ND◆	.90	.71	.51
	7500	20	—	—	300	DIP	H11D1TM-ND◆	.77	.61	.43
	7500	—	—	200	30	DIP	H11F1TVM-ND◆	2.43	2.16	1.40
	7500	1000	—	—	100	DIP	H11G1TVM-ND◆	.77	.61	.43
	7500	500	—	—	100	SMD	MOC8050TVM-ND◆	.60	.47	.34
	7500	20	—	—	70	DIP	MOC8111TM-ND◆	.53	.41	.30

† Approbation VDE ▲ Écartement entre les broches : 0,4" ‡ Bande coupée ◊ Bande et bobine ◆ ***Conforme à RoHS***

Opto-isolateurs de sortie RCS et Triac

RoHS COMPLIANT

Fig.	Tension d'isolement	Déclencheur Max IF (mA)	Tension de blocage minimale	I_{DRM} max.	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
19	5000	30	600	100nA	DIP	FOD420-ND	3.06	2.74	1.78
	5000	30	800	100nA	DIP	FOD4208-ND	2.94	2.45	1.78
	5000	30	600	100nA	DIP	FOD4216-ND	2.94	2.45	1.78
	5000	30	800	100nA	DIP	FOD4218-ND	3.91	3.27	2.38
26	5300	15	250	.100	DIP	MOC3010M-ND	.66	.52	.37
	5300	10	250	.100	DIP	MOC3011M-ND	.58	.45	.33
	5300	5	250	.100	DIP	MOC3012M-ND	.58	.45	.33
	5300	5	250	.100	SMD	MOC3012SM-ND	.68	.53	.38
	5300	30	400	.100	DIP	MOC3020MFS-ND	.66	.52	.37
	5300	15	400	.100	DIP	MOC3021MFS-ND	.73	.57	.41
	5300	10	400	.100	DIP	MOC3022MFS-ND	.62	.48	.35
	5300	10	400	.100	DIP	MOC3022VM-ND†	.66	.52	.37
	5300	5	400	.100	DIP	MOC3023MFS-ND	.62	.48	.35
	5300	5	400	.100	SMD	MOC3023SM-ND	.62	.48	.35
	5300	15	600	.100	DIP	MOC3051M-ND	.88	.72	.50
	5300	10	600	.100	DIP	MOC3052M-ND	.89	.73	.51
27	5300	15	250	.100	DIP	MOC3031M-ND	.95	.78	.54
	5300	10	250	.100	DIP	MOC3032M-ND	.88	.72	.50
	5300	5	250	.100	DIP	MOC3033M-ND	.99	.81	.56
	5300	15	400	.100	DIP	MOC3041M-ND	1.06	.87	.60
	5300	10	400	.100	DIP	MOC3042M-ND	1.06	.87	.60
	5300	5	400	.100	DIP	MOC3043M-ND	1.13	.93	.64
	5300	15	600	.500	DIP	MOC3061M-ND	1.02	.84	.58
	5300	10	600	.500	DIP	MOC3062M-ND	1.06	.87	.60
	5300	5	600	.500	DIP	MOC3063M-ND	1.01	.82	.57
	5300	5	600	.500	DIP	MOC3063TM-ND▲	1.17	.96	.66
	5300	15	800	.500	DIP	MOC3081M-ND	1.39	1.13	.79
	5300	10	800	.500	DIP	MOC3082M-ND	1.32	1.08	.75
	5300	5	800	.500	DIP	MOC3083M-ND	1.58	1.29	.89
	5300	5	600	.100	DIP	MOC3163M-ND	2.08	1.85	1.19
28	5300	60	400	100nA	SMD	MOC3023SR2MCT-ND‡	.78	.61	.44
	5300	60	400	100nA	SMD	MOC3023SR2MTR-ND◊		234.64/1,000	
	7500	60	600	100nA	SMD	MOC3052SR2VMCT-ND‡	1.05	.81	.58
	7500	60	600	100nA	SMD	MOC3052SR2VMTR-ND◊		315.59/1,000	
29	7500	60	400	100nA	SMD	MOC3043SR2MCT-ND‡	1.36	1.09	.76
	7500	60	400	100nA	SMD	MOC3043SR2MTR-ND◊		422.62/1,000	
	7500	60	600	100nA	SMD	MOC3063SR2MCT-ND‡	1.36	1.09	.76
	7500	60	600	100nA	SMD	MOC3063SR2MTR-ND◊		422.62/1,000	
30	3750	15	250	100nA	MFP	FODM3010R3VCT-ND‡	.71	.54	.41
	3750	15	250	100nA	MFP	FODM3010R3VTR-ND◊		124.51/500	
	3750	10	250	100nA	MFP	FODM3011R3VCT-ND‡	.76	.58	.43
	3750	10	250	100nA	MFP	FODM3011R3VTR-ND◊		133.40/500	
	3750	5	250	100nA	MFP	FODM3012R3VCT-ND‡	.65	.54	.44
	3750	5	250	100nA	MFP	FODM3012R3VTR-ND◊		151.19/500	
	3750	10	400	100nA	MFP	FODM3022R3VCT-ND‡	.80	.67	.54
	3750	10	400	100nA	MFP	FODM3022R3VTR-ND◊		226.78/500	
	3750	5	400	100nA	MFP	FODM3023R3VCT-ND‡	.84	.70	.56
	3750	5	400	100nA	MFP	FODM3023R3VTR-ND◊		195.66/500	
	3750	15	600	100nA	MFP	FODM3051R3VCT-ND‡	.88	.74	.59
	3750	15	600	100nA	MFP	FODM3051R3VTR-ND◊		204.55/500	
	3750	10	600	100nA	MFP	FODM3052R3VCT-ND‡	.96	.80	.64
	3750	10	600	100nA	MFP	FODM3052R3VTR-ND◊		222.34/500	
	3750	5	600	100nA	MFP	FODM3053R3VCT-ND‡	1.54	1.24	.86
	3750	5	600	100nA	MFP	FODM3053R3VTR-ND◊		291.58/500	

† Approbation VDE ▲ Écartement entre les broches : 0,4" ‡ Bande coupée ◊ Bande et bobine *(suite)*

FAIRCHILD SEMICONDUCTOR®

Opto-isolateurs

Digi-Reel®

Opto-isolateurs de sortie RCS et Triac *(suite)*

RoHS COMPLIANT

Fig.	Tension d'isolement	Déclencheur Max IF (mA)	Tension de blocage minimale	I_{DRM} max.	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
31	3750	60	250	100nA	MFP	FODM3011R1_NF098CT-ND‡	.74	.58	.42
	3750	60	250	100nA	MFP	FODM3011R1_NF098TR-ND◊		156.42/500	
	3750	60	250	100nA	MFP	FODM3012R1_NF098CT-ND‡	.84	.66	.47
	3750	60	250	100nA	MFP	FODM3012R1_NF098TR-ND◊		177.28/500	
	3750	60	600	100nA	MFP	FODM3052R1_NF098CT-ND‡	1.10	.90	.62
	3750	60	600	100nA	MFP	FODM3052R1_NF098TR-ND◊		233.26/500	
	3750	60	600	100nA	MFP	FODM3053R1_NF098CT-ND‡	1.19	.97	.67
	3750	60	600	100nA	MFP	FODM3053R1_NF098TR-ND◊		251.92/500	
32	3750	60	600	500nA	MFP	FODM3062-ND	1.53	1.25	.87
	3750	60	600	500nA	MFP	FODM3063-ND	1.69	1.37	.95
	3750	60	800	500nA	MFP	FODM3082-ND	1.92	1.71	1.10
	3750	60	800	500nA	MFP	FODM3083-ND	1.98	1.76	1.14
	7500	60	5300	100nA	SMD	MOC3021SR2MCT-ND	.78	.60	.43
36	7500	60	5300	100nA	SMD	MOC3021SR2MTR-ND		233.26/1,000	
	7500	60	5300	100nA	SMD	MOC3023SR2MCT-ND	.78	.61	.44
	7500	60	5300	100nA	SMD	MOC3023SR2MTR-ND		234.64/1,000	
	7500	60	5300	100nA	SMD	MOC3052SM-ND	.88	.72	.50
	7500	60	5300	100nA	SMD	MOC3052SR2MCT-ND	1.05	.81	.58
	7500	60	5300	100nA	SMD	MOC3052SR2MTR-ND		315.59/1,000	
	7500	60	5300	100nA	DIP	MOC3052TVM-ND	.88	.72	.50
37	7500	60	5300	100nA	SMD	MOC3043SM-ND	1.02	.84	.58
	7500	60	5300	500nA	DIP	MOC3063TVM-ND	1.17	.96	.66
	7500	60	5300	500nA	SMD	MOC3083SR2MCT-ND	1.48	1.19	.83
	7500	60	5300	500nA	SMD	MOC3083SR2MTR-ND		461.04/1,000	

† Approbation VDE ▲ Écartement entre les broches : 0,4" ‡ Bande coupée ◊ Bande et bobine

Pièces d'accouplement à 4 broches

RoHS COMPLIANT

Fig.	Isolateur Tension	Rapport de transfert de courant	V_{CEO} (max.)	tpassant/tbloqué typ. (µsec.)	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
14A	2500	50-600%	80	3/3	MFP	HMHA281-ND†	.42	.34	.26
	5000	40-80%	70	4/3	DIP	FOD617A-ND†	.43	.32	.21
	5000	63-125%	70	4/3	DIP	FOD617B-ND†	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617C-ND†	.43	.32	.21
	5000	160-320%	70	4/3	DIP	FOD617D-ND†	.43	.32	.21
14B	5000	40-80%	70	4/3	DIP	FOD617A300-ND†	.43	.32	.21
	5000	63-125%	70	4/3	DIP	FOD617B300-ND	.43	.32	.21
	5000	100-200%	70	4/3	DIP	FOD617C300-ND†	.43	.32	.21
	5000	160-320%	70	4/3	DIP	FOD617D300-ND†	.43	.32	.21
	5000	20-300%	70	4/3	DIP	FOD814-ND	.48	.38	.28
	5000	20-300%	70	4/3	SMD	FOD814S-ND	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD814SDCT-ND‡	.55	.43	.31
	5000	20-300%	70	4/3	SMD	FOD814SDTR-ND◊		329.31/2,000	
	5000	20-300%	70	4/3	DIP	FOD814W-ND▲	.44	.35	.25
	5000	20-300%	70	4/3	DIP	FOD814300-ND†	.44	.35	.25
	5000	20-300%	70	4/3	DIP	FOD814300W-ND†▲	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD8143S-ND†	.44	.35	.25
	5000	20-300%	70	4/3	SMD	FOD8143SDCT-ND†‡	.55	.43	.31
	5000	20-300%	70	4/3	SMD	FOD8143SDTR-ND†◊		329.31/2,000	
	5000	50-150%	70	4/3	DIP	FOD814A-ND	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814AS-ND	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814ASDCT-ND‡	.55	.43	.31
	5000	50-150%	70	4/3	SMD	FOD814ASDTR-ND◊		182.22/1,000	
	5000	50-150%	70	4/3	DIP	FOD814AW-ND▲	.47	.38	.27
	5000	50-150%	70	4/3	DIP	FOD814A300-ND†	.44	.35	.25
	5000	50-150%	70	4/3	DIP	FOD814A300W-ND†▲	.48	.38	.28
	5000	50-150%	70	4/3	SMD	FOD814A3S-ND†	.44	.35	.25
	5000	50-150%	70	4/3	SMD	FOD814A3SDCT-ND†‡	.55	.43	.31
	5000	50-150%	70	4/3	SMD	FOD814A3SDTR-ND†◊		182.22/1,000	
14C	2500	50-600%	7	3/3	DIP	HMHAA280R1CT-ND‡	.43	.33	.25
	2500	50-600%	7	3/3	DIP	HMHAA280R1TR-ND◊		75.89/500	
	2500	50-600%	80	3/3	MFP	HMHAA280R4VCT-ND†‡	.43	.33	.25
	2500	50-600%	80	3/3	MFP	HMHAA280R4VTR-ND†◊		352.35/2,500	
14D	5000	600-7500%	35	60/53	SMD	FOD816S-ND	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD816SDCT-ND‡	.60	.47	.34
	5000	600-7500%	35	60/53	SMD	FOD816SDTR-ND◊		198.93/1,000	
	5000	600-7500%	35	60/53	DIP	FOD816W-ND▲	.53	.42	.30
	5000	600-7500%	35	60/53	DIP	FOD816300-ND†	.53	.42	.30
	5000	600-7500%	35	60/53	DIP	FOD816300W-ND†▲	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD8163S-ND†	.53	.42	.30
	5000	600-7500%	35	60/53	SMD	FOD8163SDCT-ND†‡	.60	.47	.34
	5000	600-7500%	35	60/53	SMD	FOD8163SDTR-ND†◊		198.93/1,000	

† Approbation VDE ▲ Écartement entre les broches : 0,4" ‡ Bande coupée ◊ Bande et bobine

Opto-isolateurs de sortie logique

RoHS COMPLIANT

Fig.	Fonction	Entrée : sortie LSTTL	Configuration de sortie du débit en bauds : 15 Mo	Type de boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100	Bande et bobine◊ Qté	Prix
26	Séparateur	TTL	Totem pôle	SMD	HCPL2630S-ND	3.13	2.80	1.82	—	—
33	Séparateur	TTL	Totem pôle	SMD	FOD0708R1CT-ND‡	3.52	2.94	2.14	500	773.73
34	Séparateur	TTL	Totem pôle	SMD	FOD0710-ND	3.37	2.70	2.10	—	—
	Séparateur	TTL	Totem pôle	SMD	FOD0720-ND	2.33	1.86	1.45	—	—
	Séparateur	TTL	Totem pôle	SMD	FOD0721-ND	2.56	2.05	1.59	—	—
35	Séparateur	TTL	Totem pôle	SMD	FOD0738R1CT-ND‡	6.88	5.73	4.17	1,000	2771.21

Fig.	Tension d'isolement	Courant Ifon (max.) mA	ICCL (max.)	Tension de fonc. (max.) mV	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100	Prix de bande et bobine◊ 1 000
36	5000	1.6	7.0	2.0	SMD	FOD2200SDVCT-ND‡	2.71	2.43	1.57	981.08
37	2500	50	13	5.5	SOIC	HCPL0600-ND	2.44	2.19	1.42	—
	3750	50	13	5.5	SOIC	HCPL0601-ND	3.00	2.69	1.74	—
	2500	50	13	7.0	SMD	6N137SDCT-ND‡	1.17	.94	.65	363.71
38	2500	—	—	—	SOIC	HCPL062N-ND	5.22	4.35	3.13	—
	3750	50	13	7.0	SOICW	HCPL0637-ND	2.41	2.13	1.38	—
	3750	—	—	—	SOICW	HCPL0638-ND	2.56	2.27	1.47	—
39	2500	—	—	—	SMD	HCPL2631SDCT-ND‡	2.43	2.18	1.41	880.46
40	5300	1.6	5	16	DIP	H11L1-MQT-ND	.88	.69	.50	—
	5300	1.6	5	16	SMD	H11L1SM-ND	.95	.74	.53	—
	7500	60	5	15	SMD	H11L1SR2MCT-ND‡	1.01	.78	.56	301.87
	7500	1.6	5	15	SMD	H11L1SR2VMCT-ND‡	.99	.79	.55	307.36
	7500	1.6	5	15	SMD	H11L1SVM-ND†	.95	.74	.53	—
	7500	1.6	5	15	DIP	H11L1TM-ND	.95	.74	.53	—
	7500	1.6	5	15	DIP	H11L1TVM-ND†	.95	.74	.53	—
	5300	1.6	5	16	DIP	H11L1V-MQT-ND†	.88	.69	.49	—
	7500	1.6	5	15	DIP	H11L1VM-ND	.95	.74	.53	—
	5300	10	5	16	DIP	H11L2-MQT-ND	.58	.49	.39	—
	7500	10.0	5	15	SOIC	H11L2M-ND	.95	.74	.53	—
	7500	10.0	5	15	SMD	H11L2SM-ND	.91	.74	.52	—
	7500	10.0	5	15	SMD	H11L2SR2MCT-ND‡	.99	.79	.55	307.36
	7500	10.0	5	15	SMD	H11L2SVM-ND†	.91	.74	.52	—
	7500	10.0	5	15	DIP	H11L2TVM-ND†	.91	.74	.52	—
	7500	10.0	5	15	DIP	H11L2VM-ND†	.95	.74	.53	—
	7500	60	5	16	DIP	H11L3M-ND	.95	.74	.53	—
	5300	3.2	10	16	DIP	H11N1-MQT-ND	2.41	2.13	1.38	—
	5300	10	10	16	DIP	H11N3-M-ND	2.37	2.10	1.36	—

Fig.	Tension d'isolement	Délais de propagation max. (ns)	CMR typique V/µs	I_F (mA)	Type boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
29	2500	100	10,000	50	SMD	6N137S-ND	.95	.77	.54
	2500	100	10,000	50	SMD	HCPL0601R1CT-ND‡	3.03	2.72	1.76
	2500	100	10,000	50	SMD	HCPL0601R1TR-ND§		1098.25/1000	
41	2500	75	10,000	5	DIP	6N137QT-ND	.95	.77	.54
	2500	75	10,000	5	DIP	HCPL2601QT-ND	1.55	1.38	.89
	2500	75	10,000	5	DIP	HCPL2611-ND	1.77	1.57	1.02
42	2500	75	10,000	5	DIP	HCPL2630QT-ND	2.88	2.56	1.65
	2500	75	10,000	5	DIP	HCPL2631QT-ND	2.24	1.99	1.29

Fig.	Tension d'isolement	BVCEO minimum	tpassant/tbloqué typ. (µsec.)	Type de boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
43	2500	5	1/1	DIP	MID400-ND	2.96	2.47	1.78

◊ Pour la bande et la bobine, remplacer CT-ND par TR-ND ‡ Bande coupée § Bande et bobine † Approbation VDE

Sorties TEC

RoHS COMPLIANT

Fig.	Tension d'isolement	Rds passant (Ω)	Vbr (min.)	tpassant/tbloqué typ. (µs)	Type de boîtier	N° de référence Digi-Key	Prix unitaire 1	10	100
14A	2500	30	6	1/5	BGA	FODB100FSCT-ND‡	2.00	1.79	1.16
	2500	30	6	1/5	BGA	FODB100FSTR-ND◊		2048.05/3,000	
	2500	30	6	1/5	BGA	FODB102CT-ND‡	2.00	1.79	1.16
	2500	30	6	1/5	BGA	FODB102TR-ND◊		2048.05/3,000	
44	5000	1.5	5	2/0.3	SMDIPW	FOD3180SDCT-ND‡	1.78	1.43	1.07
45	4000	10	7	3,000/500	SMD	HSR312-ND	1.82	1.46	1.10
	4000	15	7	3,000/500	SMD	HSR312L-ND	1.82	1.46	1.10

‡ Bande coupée ◊ Bande et bobine

Panasonic®

Opto-isolateurs

RoHS COMPLIANT

Fig. 1

1. Anode
2. Cathode
3. Émetteur
4. Collecteur

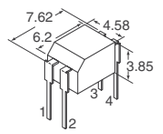
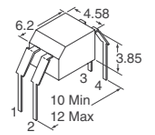


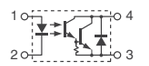
Fig. 2

1. Anode
2. Cathode
3. Émetteur
4. Collecteur

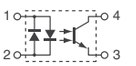


Circuits

A



B



C

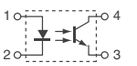


Fig.	Circuit	Tension d'isolement (V eff.)	Rapport de transfert de courant	V_{CEO} (max.)	tpassant/tbloqué standard (µs)	N° de référence Digi-Key	Prix unitaire 1	10	100
1	C	5000	80 ~ 600%	80	2/3	CNC1S101-ND	.49	.40	.30
			100 ~ 300%	80	2/3	CNC1S101R-ND	.43	.33	.25
			200 ~ 600%	80	2/3	CNC1S101S-ND	.43	.33	.25
			100 ~ 250%	80	2/3	CNC1S171R0LF-ND	.47	.36	.27
			200 ~ 600%	80	2/3	CNC1S171S0LF-ND	.47	.36	.27
	B	5000	20 ~ 300%	80	4/3	CNC7S101-ND	.61	.46	.35
			50 ~ 150%	80	4/3	CNC7S101R-ND	.65	.49	.37
			100 ~ 300%	80	4/3	CNC7S101S-ND	.65	.49	.37

Fig.	Circuit	Tension d'isolement (V eff.)	Rapport de transfert de courant	V_{CEO} (max.)	tpassant/tbloqué standard (µs)	N° de référence Digi-Key	Prix unitaire 1	10	100
1	A	5000	80 ~ 240%	80	4/3	CNC7S101Y-ND	.65	.49	.37
			1000 ~ 4000%	350	40/15	CNC2S501-ND	.72	.60	.48
			1000 ~ 4000%	350	40/15	CNZ3731-ND	.65	.55	.44
2	C	5000	100 ~ 300%	80	2/3	CNC1S101R0LF-ND	.47	.36	.27
			200 ~ 600%	80	2/3	CNC1S101S0LF-ND	.47	.36	.27
			50 ~ 600%	80	2/3	CNC1S171-ND	.60	.46	.34
			100 ~ 250%	80	2/3	CNC1S171R-ND	.43	.33	.25
			200 ~ 600%	80	2/3	CNC1S171S-ND	.43	.33	.25

N